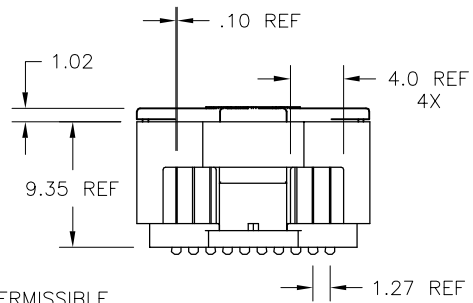
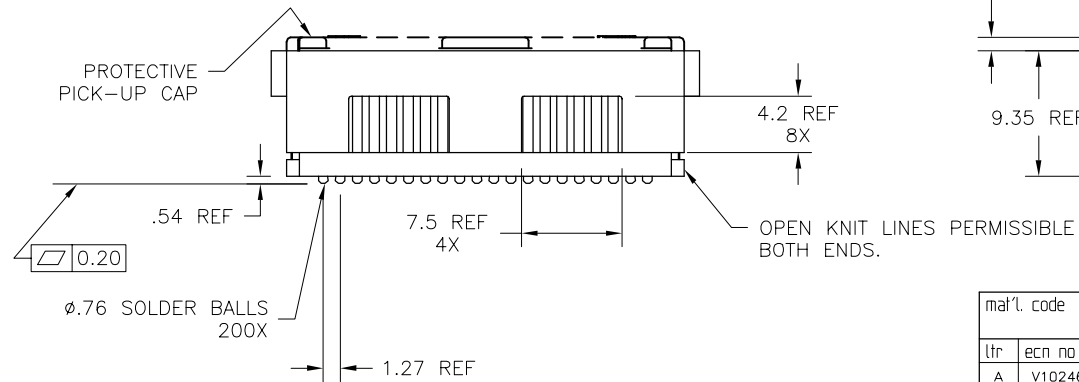
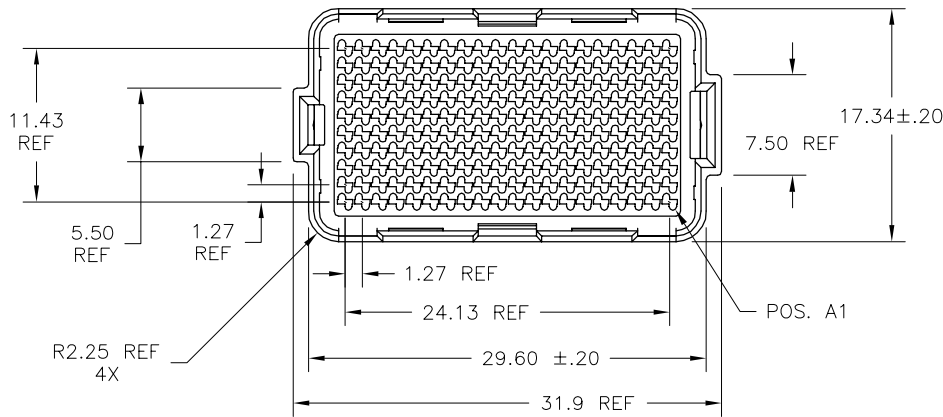
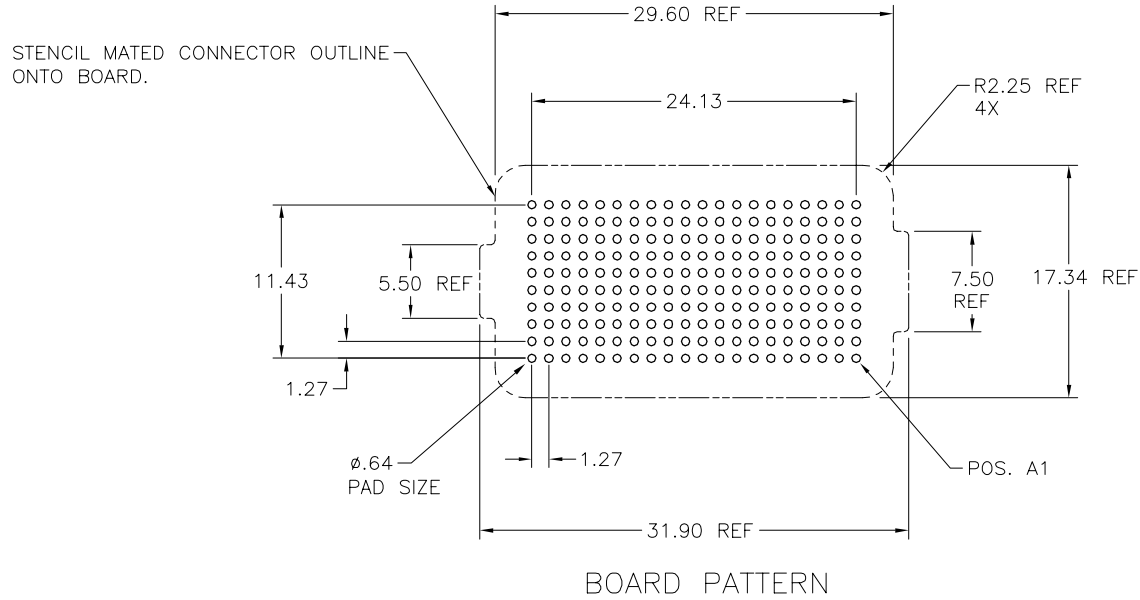


PRODUCT No.	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
84530-002	YES	15u" (.38um) Au OVER Ni	SnPb
84530-002LF			SnAgCu LEAD FREE (6)(7)
84530-102	YES	30u" (.76um) Au OVER Ni	SnPb
84530-102LF			SnAgCu LEAD FREE (6)(7)
84530-202	YES	SEE MATED HEIGHT TABLE	SnPb
84530-202LF			SnAgCu LEAD FREE (6)(7)

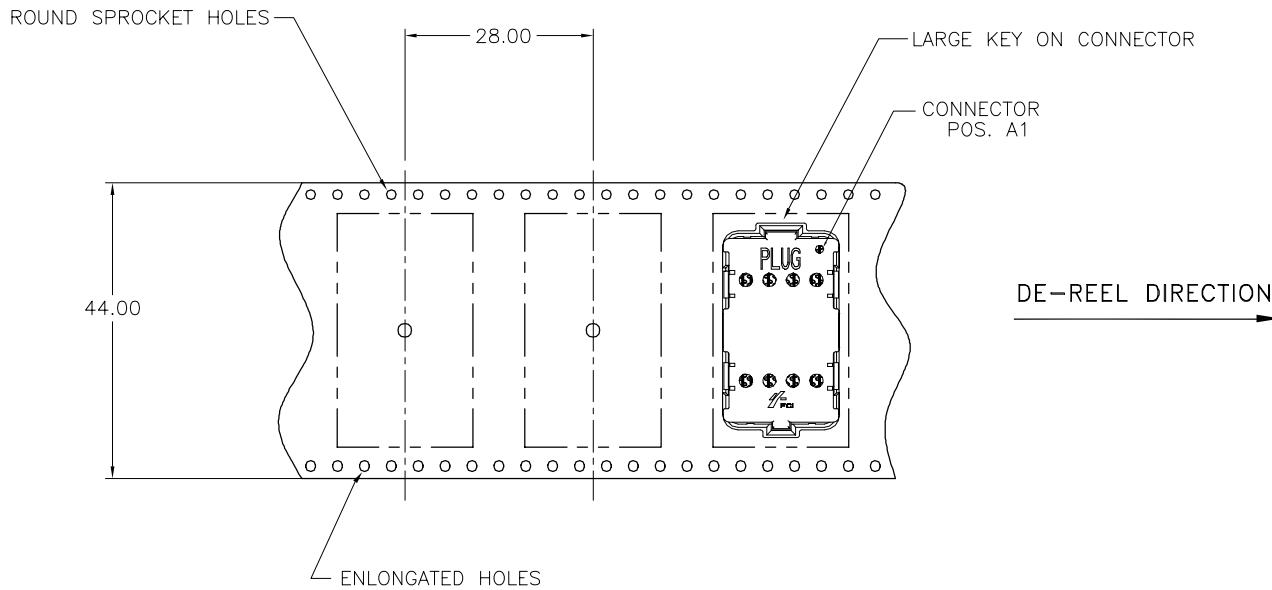


φ.76 SOLDER BALLS 200X

mat'l. code		surface		tolerance		projection		product family	
-		ASME Y14.5 ✓		ASME Y14.5				MEG-Array	
tolerances unless otherwise specified		angles		linear		MM		title	
A v10246 DRW 12.19.01		B v20006 DRW 1.10.02		C v20949 DAI 08.19.02		D v03-0681 DAI 06/20/03		6.0mm PLUG ASSY. 10 X 20 = 200 POS.	
E v04-0940 VS 10/18/04		F v06-0560 LP 2006/07/14		G v07-0641 LP 2007/10/23		D v03-0681 DAI 06/20/03		sheet 1 of 3 size	
D v03-0681 DAI 06/20/03		E v04-0940 VS 10/18/04		F v06-0560 LP 2006/07/14		G v07-0641 LP 2007/10/23		84530 A4	
sheet		revision		G G G		FCJ		type CUSTOMER Drawing	
index		sheet		1 2 3					



mat'l. code		-		surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family	MEG-Array		
ltr	ecn no	dr	date	tolerances unless otherwise specified					title			
G				angles	linear	X ±.3			6.0mm PLUG ASSY.			
				0° ±2°	XXX ±.050	scale 1:1		10 X 20 = 200 POS.				
		dr	D.WAUGHEN	9-8-99	FCI			dwg no		sheet 2 of 3	size	
		engr	B.SPINK	9-8-99	84530		A4					
		chr	B.SPINK	9-8-99	type							CUSTOMER Drawing
		appd	B.SPINK	9-8-99								
sheet index	revision sheet											



NOTES:

①. **MAT'L**
HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING
CONTACT: (SEE TABLE ON SHEET1)
SOLDER BALL: (SEE TABLE ON SHEET1)
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu

2. OVERALL BOARD-TO-BOARD STACK HEIGHTS
AVAILABLE USING THIS CONNECTOR (84530):

MATED HEIGHT	WITH RECP. P/N	-2XX PLATING
10mm	84517	SEE NOTE 2
12mm	55724	
14mm	84535	SEE NOTE 3

③. PLATING FOR INDICATED -2XX SERIES PART NOS.
MEETS THE REQUIREMENTS OF NORTEL NPS25298-2
(CENTRAL OFFICE ENVIRONMENT,
25 YEAR LIFE EXPECTANCY).

④. PLATING FOR INDICATED -2XX SERIES PART NOS. IS
Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET
REQUIREMENTS OF TELCORDIA GR-1217-CORE:
CENTRAL OFFICE ENVIRONMENT.

5. SEE SK-47384 FOR MATING RESTRICTIONS
WITH EARLIER DESIGN VERSIONS.

⑥. FOR PROPER APPLICATION FOLLOW FCI APPLICATION
SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL
NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS
DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE
PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH
LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE
FCI APPLICATION SPECIFICATION

⑦. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT
CODE NUMBER MARKED ON EACH PART BY HAVING AN "X"
IN THE SEVENTH CHARACTER POSITION

mat'l. code		-		surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family	MEG-Array
ltr	ecn no	dr	date	tolerances unless otherwise specified					title	
g				angles	X ±3	MM			6.0mm PLUG ASSY. 10 X 20 = 200 POS.	
				0° ±2°	XX ±10	scale	1:1		dwg no	
				dr	D.WAUGHEN	9-8-99		sheet 3 of 3		size
				engr	B.SPINK	9-8-99		84530		A4
				chr	B.SPINK	9-8-99		type		CUSTOMER Drawing
				appd	B.SPINK	9-8-99				
sheet	revision									
index	sheet									